



<b>PCN Number:</b>	20140327001			<b>PCN Date:</b>	03/31/2014
<b>Title:</b>	Qualification of TI Clark as Alternate Assembly/Test site for select WSON Devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	07/01/2014	<b>Estimated Sample Availability:</b>	03/31/2014		
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of CLARK AT as an alternate assembly and test site for the Select WSON devices. The material set between the existing and new site are the same.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
None					

<b>Changes to product identification resulting from this PCN:</b>						
Assembly Site						
UTAC	Assembly Site Origin (22L)	ASO: NSE				
<b>CLARK-AT</b>	Assembly Site Origin (22L)	ASO: <b>QAB</b>				
Sample product shipping label (not actual product label)						
 MADE IN: Malaysia 2DC: 20: <table border="1"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b>	MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS
MSL 2 /260C/1 YEAR	SEAL DT					
MSL 1 /235C/UNLIM	03/29/04					
<b>Topside Device marking:</b>						
Assembly site code for NSE= J						
Assembly site code for QAB= I						

Product Affected				
TLV62080DSGR	TPS62080DSGR	TPS62081DSGR	TPS62082DSGR	
TLV62080DSGT	TPS62080DSGT	TPS62081DSGT	TPS62082DSGT	

Qualification Data – Approved September, 2011				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
<b>Qual Vehicle#1: TPS62750DSK (MSL 1-260C)</b>				
Package Construction Details				
Assembly Site:	CLARK AT	Mold Compound:	4208625	
# Pins-Designator, Family:	10-DSK, WSON	Mount Compound:	4207768	
Lead Finish	NiPdAu	Bond Wire:	1.31mil Cu	
<b>Qualification:</b> <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 ATM (96 hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Visual / Mechanical	Per Manufacturing specifications	pass	pass	pass
Solderability	Steam age, 8 hours	pass	pass	pass
Notes    ** - Preconditioning sequence: Level 1-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>